

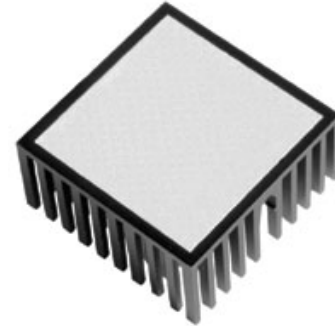


BOARD LEVEL COOLING - 3358

3358 is a series of square pin fin board level heat sinks designed to cool BGA and FPGA devices. These heat sinks use pressure sensitive adhesive for mounting. Representative image only.

ORDERING INFORMATION

Part Number	Device Type
335824B00032G	BGA, FPGA
335824B00034G	BGA, FPGA



HEAT SINK DETAILS

Property	Details
Material	Aluminum
Finish	Black Anodize
Device Attachment Options	Tape
Thermal Interface Material 335824B00032G	T405R Chomerics Tape for Metal Surfaces
Thermal Interface Material 335824B00034G	T410R Chomerics Tape for Plastic Surfaces

Property	Details
Heat Sink Width (mm)	29.97
Heat Sink Length (mm)	29.97
Heat Sink Height (mm)	9.40
Heat Sink Mounting Direction	Horizontal, Vertical

MECHANICAL & PERFORMANCE

Drawing dimensions are shown in mm, (in)

